

SOT1978-1

FBGA957, fine-pitch ball grid array package, 0.65 mm pitch,
21 mm x 21 mm x 2.37 mm body

29 May 2018

Package information

1. Package summary

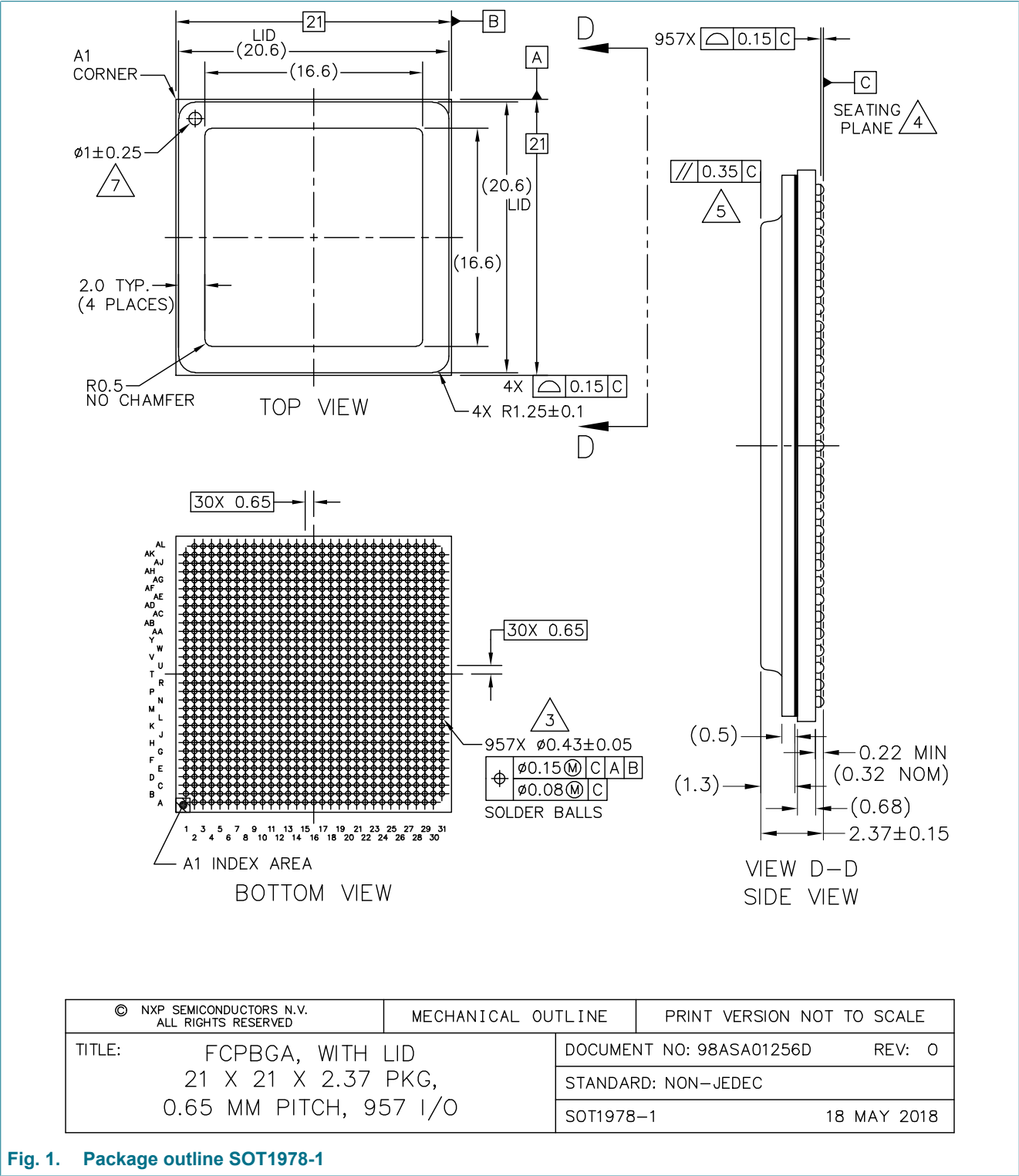
Terminal position code	B (bottom)
Package type descriptive code	FBAG957
Package style descriptive code	FBGA (fine-pitch ball grid array)
Mounting method type	S (surface mount)
Issue date	18-5-2018
Manufacturer package code	98ASA01256D

Table 1. Package summary

Parameter		Min	Nom	Max	Unit
package length		-	21	-	mm
package width		-	21	-	mm
seated height		-	2.37	-	mm
nominal pitch		-	0.65	-	mm
actual quantity of termination		-	957	-	A/A



2. Package outline



FBGA957, fine-pitch ball grid array package, 0.65 mm pitch, 21 mm x 21 mm x 2.37 mm body

- NOTES:
- 1. ALL DIMENSIONS IN MILLIMETERS.
 - 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
 - 3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C. RAW BALL DIAMETER IS 0.4MM.
 - 4. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 - 5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
 - 6. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE.
 - 7. PIN 1 THRU HOLE SHALL BE CENTERED WITHIN THE FOOT AREA.
 - 8. LID OVERHANG ON THE SUBSTRATE IS NOT ALLOWED.

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: FCPBGA, WITH LID 21 X 21 X 2.37 PKG, 0.65 MM PITCH, 957 I/O	DOCUMENT NO: 98ASA01256D REV: 0	
	STANDARD: NON-JEDEC	
	SOT1978–1	18 MAY 2018

Fig. 2. Package outline note FBGA957 (SOT1978-1)

3. Legal information

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the *Terms and conditions of commercial sale* of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

4. Contents

1. Package summary..... 1

2. Package outline..... 2

3. Legal information..... 4

© NXP B.V. 2018. All rights reserved

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: salesaddresses@nxp.com

Date of release: 29 May 2018